## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L18	939	13 and (symmetry symmetrical symmetrically)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2007/06/14 16:37
L13	6761	12 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:36
L17	573	15 and 16	US-PGPUB	OR	ON	2007/06/14 16:26
L16	26784	(pcb pwb (printed adj circuit) ((circuit wiring hybrid) adj board))[clm]	US-PGPUB	OR	ON	2007/06/14 16:26
L15	3218	((wire adj (bond bonded bonding)) wire-bond wire-bonded wire-bonding)[clm]	US-PGPUB	OR ·	ON	2007/06/14 16:25
L2	605041	pcb pwb (printed adj circuit) ((circuit wiring hybrid) adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:25
L1	71293	(wire adj (bond bonded bonding)) wire-bond wire-bonded wire-bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:25
L14	3899	13 and (method process)[clm]	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON :	2007/06/14 16:24
L12	10327	11 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:23
L11	13332	10 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:22

## **EAST Search History**

L10	24723	((wire adj (bond bonded bonding)) wire-bond wire-bonded wire-bonding) with (pad land)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:22
L9	6593	7 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/06/14 16:21
L8	2522216	etch etched etching pattern patterned patterning .	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:21
L7	7520	5 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:20
L6	2231189	protecting protective mask resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:19
L5	12614	1 and 2 and 3 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:19
L4	3588154	via through-hole feedthrough	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:18
L3	1119435	pad land	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/14 16:17